PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Toshio Saito	01/22/2008
Satoshi Moriya	01/22/2008
Morio Nakamura	01/26/2008
Goichi Yokoyama	01/22/2008
Tatsuyuki Saito	01/22/2008
Nobuaki Miyakawa	01/23/2008

RECEIVING PARTY DATA

Name:	HITACHI, LTD.
Street Address:	6-6, Marunouchi 1-chome
Internal Address:	Chiyoda-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	100-8280

Name:	HONDA MOTOR CO., LTD.	
Street Address:	1-1, Minami-Aoyama 2-chome	
Internal Address:	Minato-ku	
City:	Tokyo	
State/Country:	JAPAN	
Postal Code:	107-8556	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12063606

CORRESPONDENCE DATA

Fax Number: (703)312-6666

PATENT REEL: 022219 FRAME: 0937

500774724

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ATTORNEY DOCKET NUMBER: 843.48489X00

NAME OF SUBMITTER: Gregory E. Montone

Total Attachments: 2

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> PATENT REEL: 022219 FRAME: 0938

ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to us citizen of Japan by HITACHI, LTD. and HONDA MOTOR CO., LTD., a corporation organized under the laws of Japan, located at 6-6, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-8280, Japan and 1-1, Minami-Aoyama 2-chome, Minato-ku, Tokyo 107-8556, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD. and HONDA MOTOR CO., LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR DEVICE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD. and HONDA MOTOR CO., LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings; or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD. and HONDA MOTOR CO., LTD.,

Signed on the date(s) indicated aside signatures:

INVENTOR(S) (発明者フルネームサイン)		Date Signed (署名日)
1)	Toshio Saito (Toshio SAITO)	1/22/2008
2)	Satoshi moringa (Satoshi MORIYA)	1/22/2008
	Merio nakamura (Morio NAKAMURA)	1/26/2008
- ,	Goichi Yokoyama (Goichi YOKOYAMA)	1/22/2008
	Tatsuyuki Sait (Tatsuyuki SAITO)	1/22/2008
	(Nobuaki MIYAKAWA)	
7)		
8)		

PATENT REEL: 022219 FRAME: 0939

ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to us citizen of Japan by HITACHI, LTD. and HONDA MOTOR CO., LTD., a corporation organized under the laws of Japan, located at 6-6, Marunouchi 1-chome, Chiyoda-ku, Tokyo 100-8280, Japan and 1-1, Minami-Aoyama 2-chome, Minato-ku, Tokyo 107-8556, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD. and HONDA MOTOR CO., LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

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invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD. and HONDA MOTOR CO., LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD. and HONDA MOTOR CO., LTD.,

Signed on the date(s) indicated aside signatures:

RECORDED: 02/06/2009

INVENTOR(S) (発明者フルネームサイン)		Date Signed (署名日)	
1)	(Toshio SAITO)		
2)	(Satoshi MORIYA)		
3)	(Morio NAKAMURA)		
4)	(Goichi YOKOYAMA)		
5)			
6)	Nobuski Miyekava (Nobuski MIYAKAWA)	January 28, 2008	
7)			
8)			

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